

CHALLENGES

Charge Decay monitoring

Field Meter measurement

Powder coating test set

Conduction to ground monitoring

NEXT GENERATION ELECTONIC DEVICES – ORGANIC, OXIDE & GRAPHENE-RELATED

SOLUTIONS

Identify chemicals and study degradation Determine molecular weight of polymers for device ✓ Fourier Transform Infrared Analysis Chemical Analysis / Study glass transitions for optimal process temperatures ✓ Gel Permeation Chromatography Chemical and thermal analysis of organic material; Polymer ✓ Differential Scanning Calorimetry ✓ Thermal Gravimetric Analysis temperature rating Qualitative chemical measurements Wet Chemical Analysis Optical properties of materials ✓ UV-Visible-IR optics spectrometer Estimation of carrier concentration in TCOs ✓ Atomic Force Microscope LED spectral performance Surface height/roughness; accuracy of manufacturing steps Visible inspection of defects/failures ✓ High Magnification Optical Microscopes Large area cross section cutting, large area patterning ✓ Laser Isolation/patterning equipment Removal of organic compounds/surface cleaning ✓ Plasma Etcher ✓ Probe Stations for Device Characterisation Device characterisation Cross sectional analysis, circuit editing ✓ Class 'A' solar simulator and light soakers Multiple low noise electrical measurements Focussed Ion Beam/SEM Depth profiling, identifying contaminants/impurities Switch Matrix Surface cleaning, surface mapping of elements TOF-SIMS Electronic Test Electrical / Low noise IV measurements ✓ Agilent Femto-Amp resolution parameter analysers ✓ RLC bridges impedance measurements Gate dielectric, contacts, carrier transport properties Automated, multiple low noise electrical measurements ✓ Automated Test Equipment **Environmental** ✓ Outdoor test rigs for solar modules Accelerated tests ✓ Weather station and irradiance sensor **UV** degradation Testing for delamination, yellowing, cracking, colour ✓ Environmental Chambers ✓ Light soaking External visual inspection for cracks/failures/defects Electron Microscopy/ ✓ Field Emission Scanning Electron Microscopy **Surface Analysis** Elemental analysis ✓ Energy Dispersive X-ray Spectroscopy Gate oxide properties, semiconductor surface structure ✓ Atomic Force Microscopy Work function calculations ✓ Kelvin probe microscopy Molecular ordering ✓ X-ray Diffraction Optical constants, non-destructive change to optical Ellipsometry properties Focussed Ion Beam (via partner) Cross sectional analysis, failure analysis Fabrication of Organic/unstable devices √ Vacuum Furnaces up to 600 C Patterning of interconnects ✓ Photolithography Materials Metallisation/dielectric deposition √ 3-source sputter coater Electrical contact/dielectric/AR coating ✓ Electron Beam deposition Electrical contact/dielectric/AR coating Thermal evaporation of metals, organic materials Step heights Class 1000 cleanroom Surface roughness ✓ Atomic Force Microscpe Destructive Analysis Gate oxide properties, semiconductor surface structure ✓ Probe station, surface analysis equipment - AFM Work function calculations Probe station, surface analysis equipment - KFM Molecular ordering Probe station, surface analysis equipment - XRD Surface resistivity measurement ✓ Surface resistivity measurement **Electrostatic**

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